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FDMS7558S

October 2014

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2 S 1 S

N-Channel PowerTrench[®] SyncFETTM 25 V, 49 A, 1.25 m Ω

Features

- Max $r_{DS(on)} = 1.25 \text{ m}\Omega$ at $V_{GS} = 10 \text{ V}$, $I_D = 32 \text{ A}$
- Max $r_{DS(on)} = 1.75 \text{ m}\Omega$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 28 \text{ A}$
- Advanced Package and Silicon combination for low r_{DS(on)} and high efficiency
- SyncFET Schottky Body Diode
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

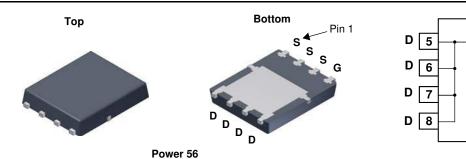


General Description

The FDMS7558S has been designed to minimize losses in power conversion application. Advancements in both silicon and package technologies have been combined to offer the lowest $r_{\text{DS}(\text{on})}$ while maintaining excellent switching performance. This device has the added benefit of an efficient monolithic Schottky body diode.

Applications

- Synchronous Rectifier for Synchronous Buck Converters
- Notebook
- Server
- Telecom
- High Efficiency DC-DC Switch Mode Power Supplies



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units	
V_{DS}	Drain to Source Voltage			25	V	
V_{GS}	Gate to Source Voltage		(Note 4)	±20	V	
	Drain Current -Continuous (Package limited)	T _C = 25 °C		49		
	-Continuous (Silicon limited)	T _C = 25 °C		199	^	
ID	-Continuous	T _A = 25 °C	(Note 1a)	32	A	
	-Pulsed			180		
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	288	mJ	
D	Power Dissipation	T _C = 25 °C		89	14/	
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1a)	2.5	W	
T _J , T _{STG}	Operating and Storage Junction Temperature R	ange		-55 to +150	°C	

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	50	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMS7558S	FDMS7558S	Power 56	13 "	12 mm	3000 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	I _D = 1 mA, V _{GS} = 0 V	25			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 10 mA, referenced to 25 °C		21		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 20 V, V _{GS} = 0 V			500	μΑ
I _{GSS}	Gate to Source Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA

On Characteristics (Note 2)

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$	1.2	1.6	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 10 mA, referenced to 25 °C		-5		mV/°C
r _{DS(on)}		$V_{GS} = 10 \text{ V}, I_D = 32 \text{ A}$		1.0	1.25	
	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 28 \text{ A}$		1.4	1.75	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 32 \text{ A}, T_J = 125 \text{ °C}$		1.4	1.8	1
9 _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 32 \text{ A}$		221		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 10 V V 0 V	5843	7770	pF
C _{oss}	Output Capacitance	$V_{DS} = 13 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$	1615	2150	рF
C _{rss}	Reverse Transfer Capacitance	1 – 1 1011 12	317	475	pF
R _a	Gate Resistance		0.5	1.0	Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time		18	33	ns
t _r	Rise Time	V _{DD} = 13 V, I _D = 32 A,	9	18	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	44	70	ns
t _f	Fall Time		5	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	85	119	nC
Qg	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 13 \text{ V}$,	39	55	nC
Q _{gs}	Gate to Source Gate Charge	I _D = 32 A	16.5		nC
Q_{gd}	Gate to Drain "Miller" Charge		9.7		nC

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 2 \text{ A}$ (Note 2)	0.38	0.7	V
	Source to Drain Diode Forward voltage	V _{GS} = 0 V, I _S = 32 A (Note 2)	0.75	1.2	
t _{rr}	Reverse Recovery Time	-I _E = 32 A, di/dt = 300 A/μs	39	63	ns
Q _{rr}	Reverse Recovery Charge	$I_F = 32 \text{ A}, \text{ di/dt} = 300 \text{ A/}\mu\text{S}$	52	84	nC

^{1.} $R_{\theta JA}$ is determined with the device mounted on a $1in^2$ pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a. 50 °C/W when mounted on a 1 in² pad of 2 oz copper.



 b. 125 °C/W when mounted on a minimum pad of 2 oz copper.

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. E_{AS} of 288 mJ is based on starting T_J = 25 °C, L = 1 mH, I_{AS} = 24 A, V_{DD} = 23 V, V_{GS} = 10 V. 100% test at L = 0.3 mH, I_{AS} = 35 A.
- 4. As an N-ch device, the negative Vgs rating is for low duty cycle pulse occurrence only. No continuous rating is implied.

Typical Characteristics T_J = 25 °C unless otherwise noted

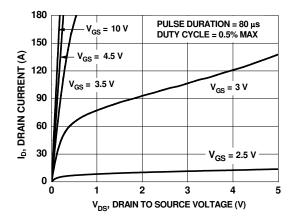


Figure 1. On Region Characteristics

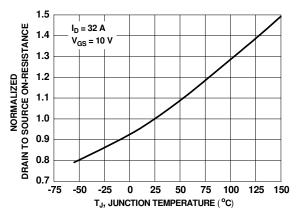


Figure 3. Normalized On Resistance vs Junction Temperature

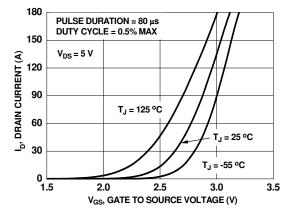


Figure 5. Transfer Characteristics

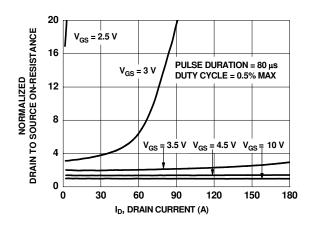


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

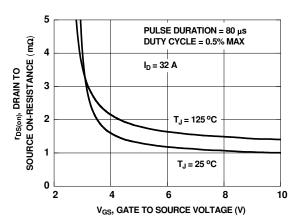


Figure 4. On-Resistance vs Gate to Source Voltage

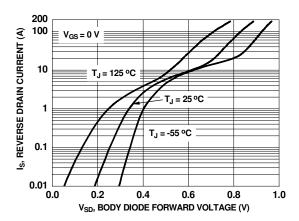


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

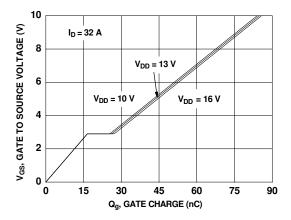


Figure 7. Gate Charge Characteristics

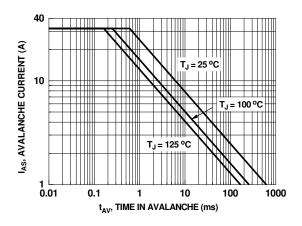


Figure 9. Unclamped Inductive Switching Capability

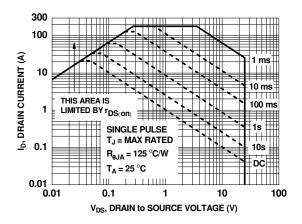


Figure 11. Forward Bias Safe Operating Area

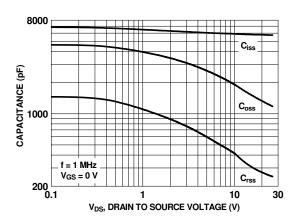


Figure 8. Capacitance vs Drain to Source Voltage

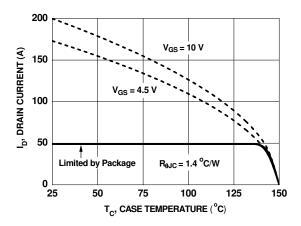


Figure 10. Maximum Continuous Drain Current vs Case Temperature

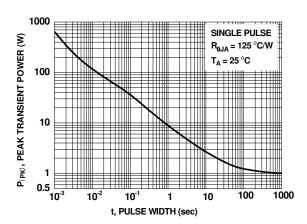


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

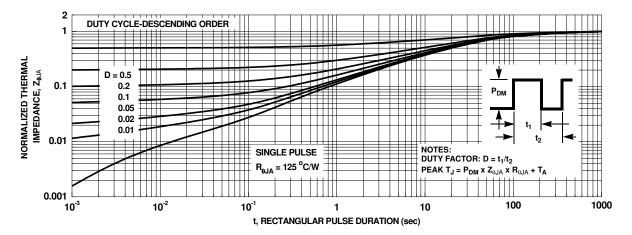


Figure 13. Junction-to-Ambient Transient Thermal Response Curve

Typical Characteristics (continued)

SyncFET Schottky body diode Characteristics

Fairchild's SyncFET process embeds a Schottky diode in parallel with PowerTrench MoSFET. This diode exhibits similar characteristics to a discrete external Schottky diode in parallel with a MOSFET. Figure 14 shows the reverses recovery characteristic of the FDMS7558S.

Schottky barrier diodes exhibit significant leakage at high temperature and high reverse voltage. This will increase the power in the device.

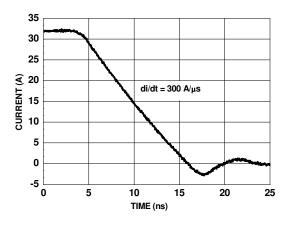


Figure 14. FDMS7558S SyncFET body diode reverse recovery characteristic

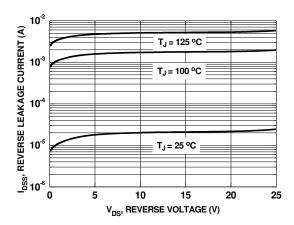
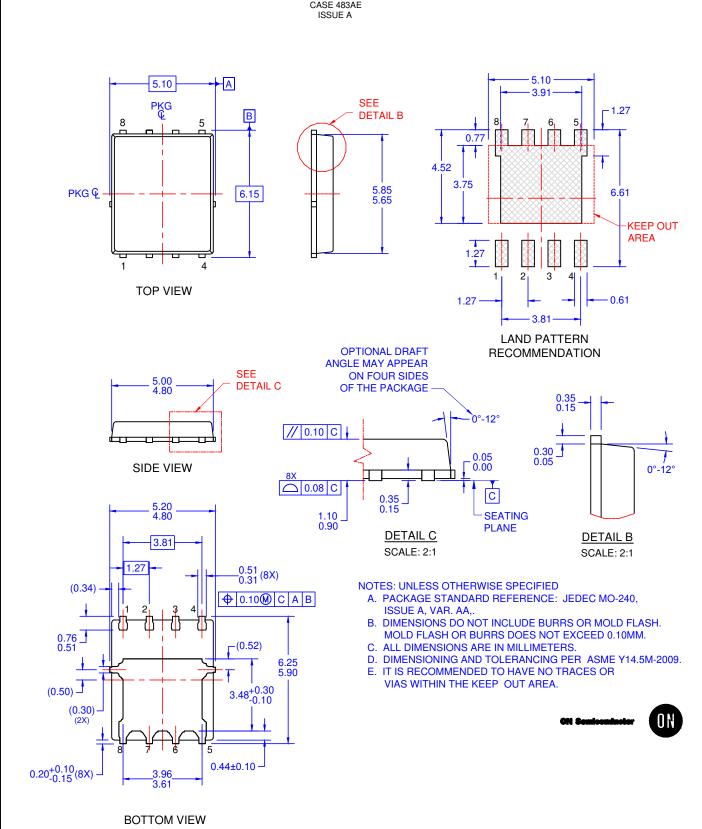


Figure 15. SyncFET body diode reverses leakage versus drain-source voltage



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